In the Claims:

Please amend the claims as follows:

Please replace pending claim 1 with the following claim having the same number, and replacement claim 1 is also shown in re-written form, with underlining showing additions, on a sheet attached to this Amendment and filed herewith:

1 (twice amended). An integrated package comprising:

a substrate having a plurality of peripheral openings and first and second surfaces;

a chip adhered to said second surface of said substrate;

a plurality of electrical conductors physically attached to said chip and located such that

5   each electrical conductor in said plurality of electrical conductors is aligned within a respective

one of said plurality of peripheral openings in said substrate;

a plurality of pads disposed on said first surface of said substrate generally centralized within said peripheral openings of said substrate; and

potting material filling said peripheral openings.

Please replace pending claim 6 with the following claim having the same number, and replacement claim 6 is also shown in re-written form, with underlining showing additions, on a sheet attached to this Amendment and filed herewith:

6 (amended). The integrated circuit package as recited in claim 1 further comprising a plurality of solder balls disposed on said pads.

Please add the following new claim 21:

-- 21. The integrated circuit package of claim 1 wherein each of the plurality of conductors comprises a bonding pad. --.

[Please add the following new claim 22:]

-- 22. An integrated package comprising:

a substrate having a plurality of peripheral opening and first and second surfaces;

a chip comprising an operative side and a non-operative side, wherein said chip is adhered to said second surface of said substrate such that the non-operative side faces away from the substrate;

a plurality of pads disposed on said first surface of said substrate generally centralized within said peripheral openings of said substrate; and

potting material filling said peripheral openings. --

REMARKS

Claims 1 through 20 were already pending in this case. The present Amendment amends the Specification, and also amends independent claims 1, 8, and 16, and makes a typographical correction to dependent claim 15. New dependent claim 21 and new independent claim 22 are added. Reconsideration and favorable action in the above-referenced application, based on the present amendments thereto and the following remarks, are respectfully requested.

Amendments to the Specification

The present Amendment makes a typographical change to page 23, line 7.

Amendment to the Drawings

Applicant submits herewith a Request For Approval To Amend Drawings consistent with the request of the Examiner.

4

Please replace pending claim 16 with the following claim having the same number, and replacement claim 16 is also shown in re-written form, with underlining showing additions, on a sheet attached to this Amendment and filed herewith:

16 (twice amended). An integrated circuit package comprising:

a substrate having a plurality of peripheral openings, first and second surfaces and an outline;

a plurality of routing strips being integral with said substrate;

5   a plurality of pads centrally disposed on said first surface at least one of said pads being electrically connected with said routing strips;

a chip adhered to said second surface of said substrate, said chip having an outline that is substantially the same as said outline of said substrate and having a plurality of bonding pads physically attached to the chip and located such that each bonding pad in said plurality of

10   bonding pads is aligned within a respective one of said plurality of peripheral openings in said substrate;

wire bonding electrically connecting said bonding pads to said routing strips;

vias connecting said routing strips to said pads;

potting material filling said peripheral openings and covering said wire bonding and

15   said bonding pads; and

a plurality of solder balls centrally disposed on said pads disposed on said first surface of said substrate.

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